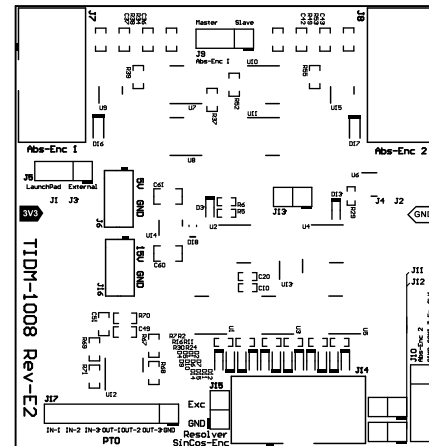
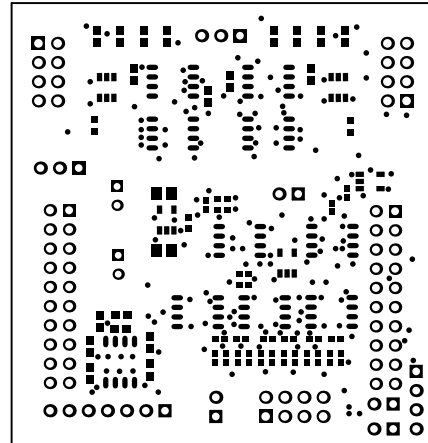


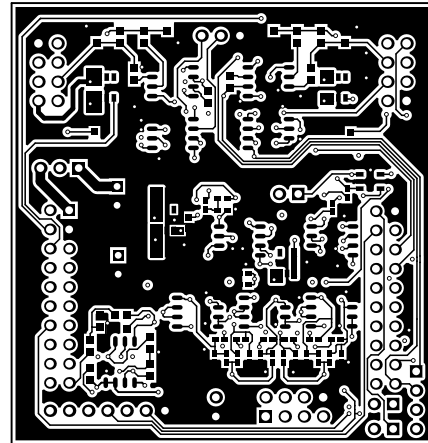
Top Overlay



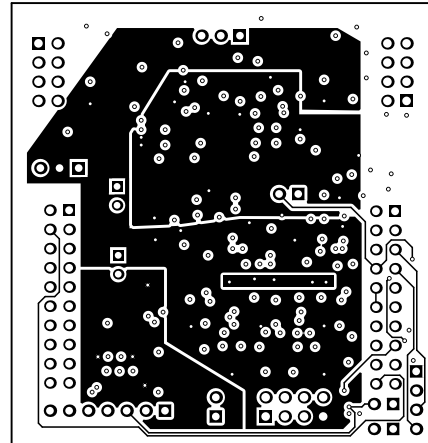
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDM-1008		
PLOT NAME = Top Overlay	GENERATED : 8/11/2017 4:48:26 PM	TEXAS INSTRUMENTS	



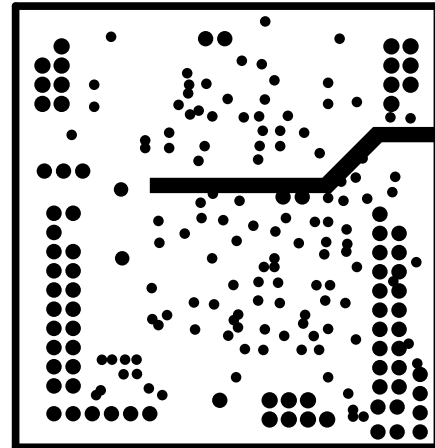
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDM-1008		
PLOT NAME = Top Solder Mask	GENERATED : 8/11/2017 4:48:26 PM	TEXAS INSTRUMENTS	



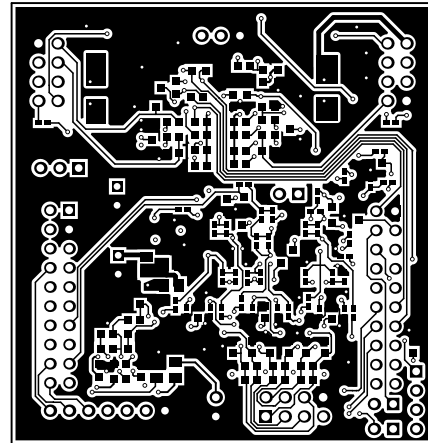
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDM-1008		
PLOT NAME = Top Layer	GENERATED : 8/11/2017 4:48:26 PM	TEXAS INSTRUMENTS	



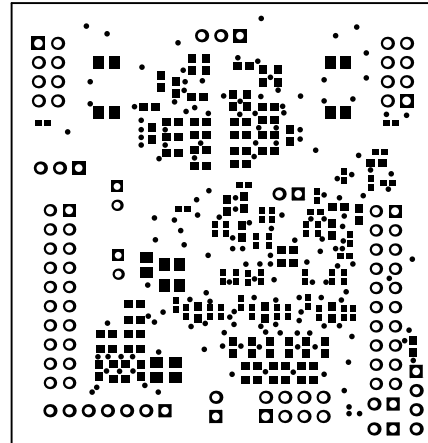
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDM-1008		
PLOT NAME = Power Plane	GENERATED : 8/11/2017 4:48:26 PM	TEXAS INSTRUMENTS	



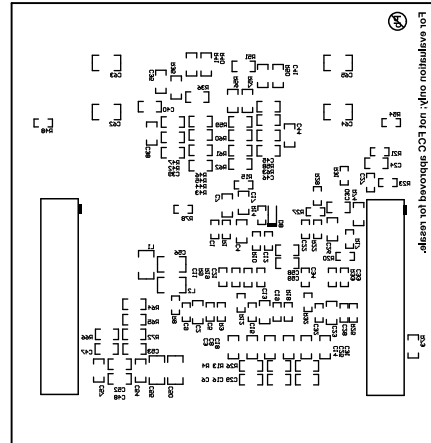
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDM-1008		
PLOT NAME = Ground Plane	GENERATED : 8/11/2017 4:48:26 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDM-1008		
PLOT NAME = Bottom Layer	GENERATED : 8/11/2017 4:48:26 PM	TEXAS INSTRUMENTS	



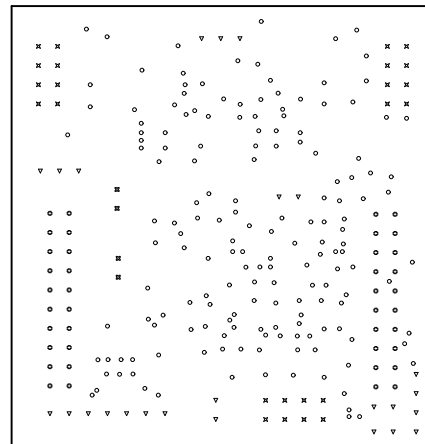
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDM-1008		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/11/2017 4:48:26 PM	TEXAS INSTRUMENTS	



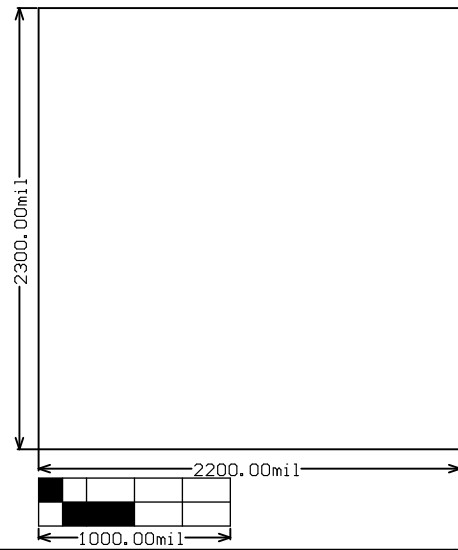
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDM-1008		
PLOT NAME = Bottom Overlay	GENERATED : 8/11/2017	4:48:26 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Fractional Hole Size	Plated	Plk. Type	Drill Layer Pair	Hide Tabernacle
○	107	15.14mm (0.596mm)	PTH	Plated	Top Layer - Bottom Layer	
■	4	35.41mm (1.394mm)	PTH	Plated	Top Layer - Bottom Layer	
▽	20	40.25mm (1.585mm)	PTH	Plated	Top Layer - Bottom Layer	
○	85	30.20mm (1.189mm)	PTH	Plated	Top Layer - Bottom Layer	
■	24	44.28mm (1.743mm)	PTH	Plated	Top Layer - Bottom Layer	
<b>Total Holes</b>						



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDM-1008		
PLOT NAME = Drill Drawing	GENERATED : 8/11/2017	4:48:26 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1008	REV: 002	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDM-1008		
PLOT NAME = Board Dimensions	GENERATED : 8/11/2017	4:48:27 PM	TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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